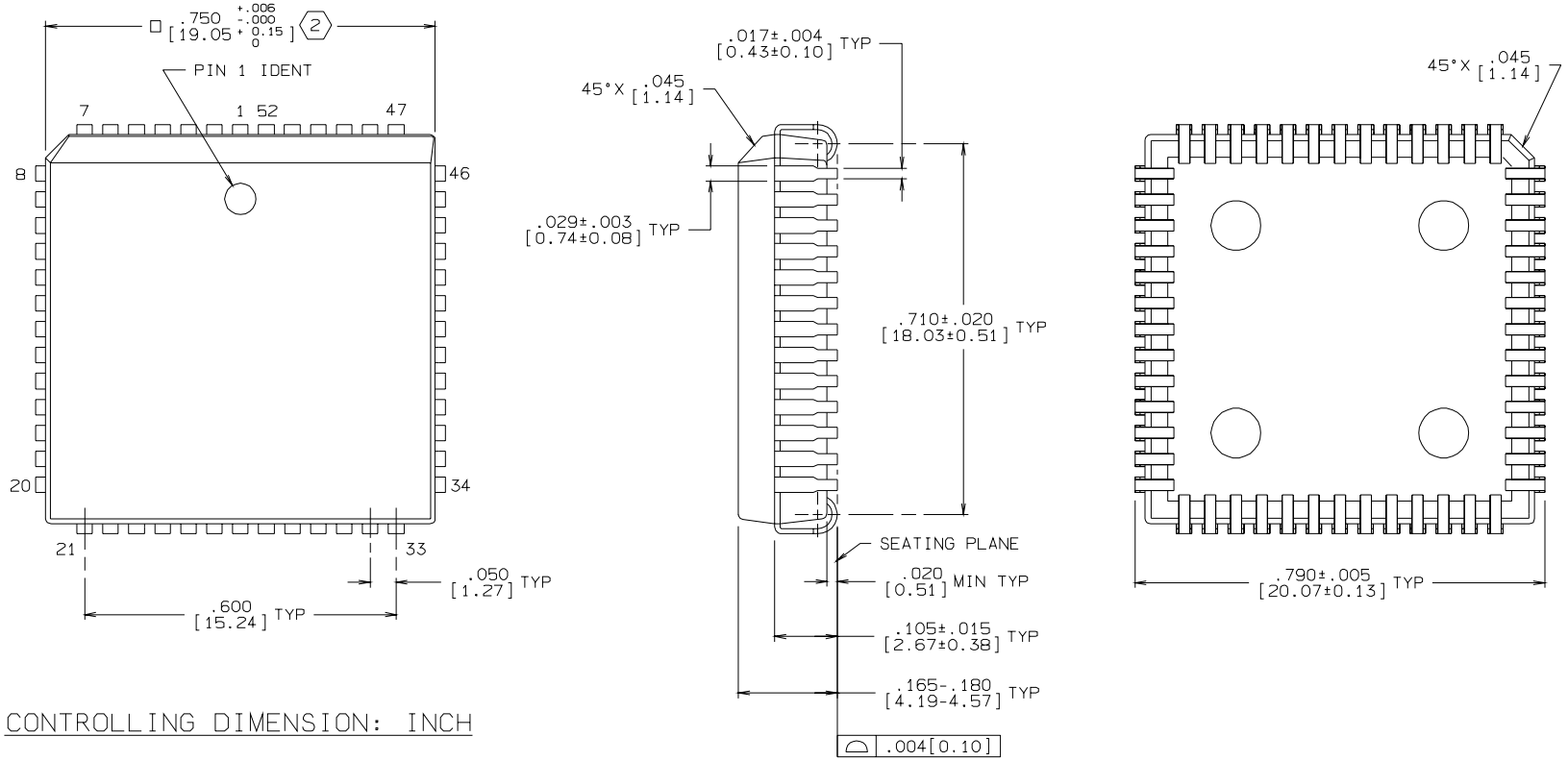
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	05067	06/22/87	SCH/
B	.020 MIN WAS .040/.018	05593	04/05/88	YT/KS
C	NOTE 2: .012in/0.30mm WAS .010in/0.25mm	05984	08/15/88	GVZ/CO
D	REMOVE CASTELLATION; REVISE & REDRAW PER CURRENT STD	09324	09/16/92	TL/SL
E	ADD COPLANARITY & SEATING PLANE; CONVERT LIMIT DIM'S TO NOM±TOL.	10033	12/03/93	MS/



CONTROLLING DIMENSION: INCH

NOTES: UNLESS OTHERWISE SPECIFIED

1. STANDARD LEAD FINISH:
   200 MICROINCHES / 5.08 MICROMETERS MINIMUM SOLDER THICKNESS PER SIDE ON COPPER (Cu).

(2) DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
   MAXIMUM ALLOWABLE MOLD PROTRUSION .010 IN / 0.25 mm PER SIDE.

3. REFERENCE JEDEC REGISTRATION MO-047, VARIATION AD, DATED 5/90.

APPROVALS	DATE
DRAWN T. LEQUANG	09/16/92
DFTG. CHK.	
ENGR. CHK.	
APPROVAL	

PROJECTION INCH [MM]

NATIONAL SEMICONDUCTOR CORPORATION
2900 Semiconductor Drive, Santa Clara, CA 95052-8090

PLASTIC CHIP CARRIER, SQ, .050 LD PITCH, 52 LEAD

SCALE	SIZE	DRAWING NUMBER	REV
N/A	C	MKT-V52A	E

DO NOT SCALE DRAWING | SHEET 1 OF 1